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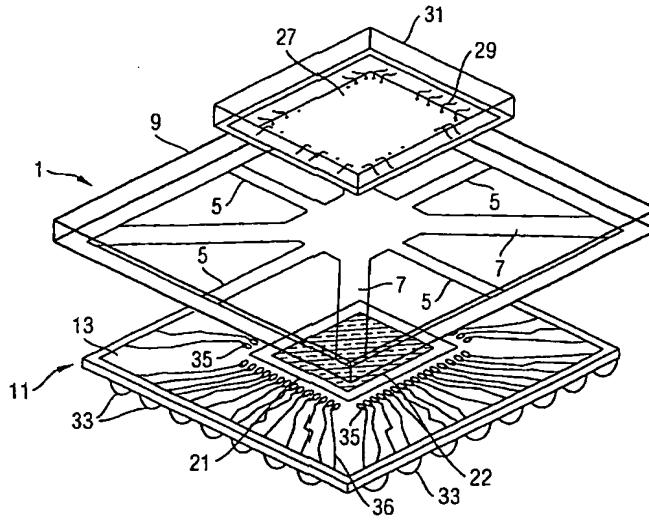
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(54) Title: HEAT DISSIPATION DEVICE FOR INTEGRATED CIRCUITS



(57) Abstract: An integrated circuit (27, 67) is packaged by mounting it onto a substrate (11, 55) with a heat conductive plate (1, 41) interposed between the integrated circuit (27, 67) and the substrate (11, 55). The plate (1, 41) has portions (5, 7, 9) extending laterally out from under the integrated circuit, and these portions conduct away heat generated by the integrated circuit (27, 67). The plate (1, 41) may be connected to ground, and be connected by wire bonding to pads of the integrated circuit (27, 67) which are to be grounded. In one arrangement, the plate (1) may be located above a second integrated circuit such as a flipchip (22). In another arrangement, a plurality of integrated circuits (67) may be connected to the substrate (55) via the plate (41), and the substrate (55) and plate (41) singulated together to form a plurality of packages.